

2. Specification

2-1. GSM General Specification

	GSM850	EGSM 900	DCS1800	PCS1900	WCDMA 2100	WCDMA 1900	WCDMA 900	WCDMA 850
Freq. Band[MHz] Uplink/ Downlink	824~849 869~894	880~915 925~960	1710~1785 1805~1880	1850~1910 1930~1990	1922~1977 2112~2167	1852~1907 1932~1987	880~915 925~960	824~849 869~894
ARFCN range	128~251	0~124 & 975~1023	512~885	512~810	UL: 9612~9888 DL: 10562~10838	UL: 9262~9538 DL: 9662~9938	UL: 2712~2863 DL: 2937~3088	UL: 4132~4233 DL: 4357~4458
Tx/Rx spacing	45MHz	45MHz	95MHz	80MHz	190MHz	80MHz	45MHz	45MHz
Mod. Bit rate/ Bit Period	270.833kbp s 3.692us	270.833kbp s 3.692us	270.833kbp s 3.692us	270.833kbp s 3.692us	3.84Mcps	3.84Mcps	3.84Mcps	3.84Mcps
Time Slot Period/ Frame Period	576.9us 4.615ms	576.9us 4.615ms	576.9us 4.615ms	576.9us 4.615ms	FrameLength: 10ms Slotlength: 0.667ms	FrameLength: 10ms Slotlength: 0.667ms	FrameLength: 10ms Slotlength: 0.667ms	FrameLength: 10ms Slotlength: 0.667ms
Modulation	0.3GMSK	0.3GMSK	0.3GMSK	0.3GMSK	QPSKHQPSK	QPSKHQPSK	QPSKHQPSK	QPSKHQPSK
MS Power	33dBm~5dBm	33dBm~5dBm	30dBm~0dBm	30dBm~0dBm	24dBm~ -50dBm	24dBm~ -50dBm	24dBm~ -50dBm	24dBm~ -50dBm
Power Class	5pcl ~ 19pcl	5pcl ~ 19pcl	0pcl ~ 15pcl	0pcl ~ 15pcl	3(max+24dBm)	3(max+24dBm)	3(max+24dBm)	3(max+24dBm)
Sensitivity	-102dBm	-102dBm	-100dBm	-100dBm	-106.7dBm	-106.7dBm	-106.7dBm	-106.7dBm
TDMA Mux	8	8	8	8	8	8	8	8
Cell Radius	35Km	35Km	2Km	2Km	2Km	2Km	2Km	2Km

2. Specification

2-2. GSM Tx Power Class

TX Power control level	GSM850	TX Power control level	EGSM900	TX Power control level	DCS1800	TX Power control level	PCS1900
5	33±2 dBm	5	33±2 dBm	0	30±3 dBm	0	30±3 dBm
6	31±2 dBm	6	31±2 dBm	1	28±3 dBm	1	28±3 dBm
7	29±2 dBm	7	29±2 dBm	2	26±3 dBm	2	26±3 dBm
8	27±2 dBm	8	27±2 dBm	3	24±3 dBm	3	24±3 dBm
9	25±2 dBm	9	25±2 dBm	4	22±3 dBm	4	22±3 dBm
10	23±2 dBm	10	23±2 dBm	5	20±3 dBm	5	20±3 dBm
11	21±2 dBm	11	21±2 dBm	6	18±3 dBm	6	18±3 dBm
12	19±2 dBm	12	19±2 dBm	7	16±3 dBm	7	16±3 dBm
13	17±2 dBm	13	17±2 dBm	8	14±3 dBm	8	14±3 dBm
14	15±2 dBm	14	15±2 dBm	9	12±4 dBm	9	12±4 dBm
15	13±2 dBm	15	13±2 dBm	10	10±4 dBm	10	10±4 dBm
16	11±3 dBm	16	11±3 dBm	11	8±4 dBm	11	8±4 dBm
17	9±3dBm	17	9±3dBm	12	6±4 dBm	12	6±4 dBm
18	7±3 dBm	18	7±3 dBm	13	4±4 dBm	13	4±4 dBm
19	5±3 dBm	19	5±3 dBm	14	2±5 dBm	14	2±5 dBm
				15	0±5 dBm	15	0±5 dBm

2. Specification

2-3. LTE General Specification

	LTE Band1	LTE Band3	LTE Band5	LTE Band7	LTE Band8	LTE Band20
Freq. Band[MHz] Uplink/ Downlink	1920~1980 2110~2170	1710~1785 1805~1880	824~849 869~894	2500~2570 1805~1880	880~914.9 925~959.9	832~862 791~821
ARFCN range	UL: 18000~18599 DL: 0~599	UL: 19200~19950 DL: 1805~1880	UL: 20400~20649 DL: 2400~2649	UL: 20750~21449 DL: 2750~3449	UL: 21450~21799 DL: 3450~3799	UL: 24150~24450 DL: 6150~6450
Tx/Rx spacing	190MHz	95MHz	45MHz	120MHz	45MHz	41MHz
Channel Bandwidth	60 MHz	75 MHz	25 MHz	70 MHz	1.4/3/5/10MHz	5/10/15/20 MHz
Modulation	QPSK,16/64Q AM	QPSK,16/64Q AM	QPSK,16/64Q AM	QPSK,16/64Q AM	QPSK,16/64Q AM	QPSK,16/64Q AM
MS Power (MPR)	-35~25.7 dBm	-35~25.7 dBm	-35~25.7 dBm	-35~25.7 dBm	-35~25.7 dBm	-35~25.7 dBm
Sensitivit (QPSK) (BW 10MHz)	-94 dBm	-92 dBm	-92 dBm	-95dBm	-95dBm	-94dBm
Cell Radius	>5Km	>5Km	>5Km	>5Km	>5Km	>5Km

2. Specification

	LTE Band 38	LTE Band 40
Freq. Band[MHz] Uplink/ Downlink	2570~2620	2300~2400
ARFCN range	UL, DL : 2570~2620	UL, DL : 2300~2400
Tx/Rx spacing	-	-
Channel Bandwidth	5/10/15/20 MHz	5/10/15/20 MHz
Modulation	QPSK,16/64QAM	QPSK,16/64QAM
MS Power (MPR)	-35~25.7 dBm	-35~25.7 dBm
Sensitivit (QPSK) (BW 10MHz)	-97dBm	-97dBm
Cell Radius	>5Km	>5Km

3. Operation Instruction and Installation

Main Function

Item	Description
OS	Android V6.0.1 (Marshmallow OS)
RF	2G Quad(850/900/1800/1900), WCDMA(1,2,5,8), LTE (1,3,5,7,8,20,38,40)
Battery	2,800mAh
Base Band	1.4GHz Quad-Core
Other RF	GPS, Glonass, Beidou, BT4.2, USB 2.0, WIFI 802.11 b/g/n 2.4+5GHz
Camera	13MP AF (Main). 5M FF(Front)
LCD	5" HD TFT LCD, 1280 x 720
RAM	2GB LPDDR3 RAM + 16GB eMMC
Sensor	Accelerometer, Proxy, Magnetic
Accessory	Charger: 5V, 1.55A Headset (Option)

9. Reference Abbreviate

Reference Abbreviate

- **AAC**: Advanced Audio Coding.
- **AVC** : Advanced Video Coding.
- **BER** : Bit Error Rate
- **BPSK**: Binary Phase Shift Keying
- **CA** : Conditional Access
- **CDM** : Code Division Multiplexing
- **C/I** : Carrier to Interference
- **DMB** : Digital Multimedia Broadcasting
- **EN** : European Standard
- **ES** : Elementary Stream
- **ETSI**: European Telecommunications Standards Institute
- **MPEG**: Moving Picture Experts Group
- **PN** : Pseudo-random Noise
- **PS** : Pilot Symbol
- **QPSK**: Quadrature Phase Shift Keying
- **RS** : Reed-Solomon
- **SI** : Service Information
- **TDM** : Time Division Multiplexing
- **TS** : Transport Stream

1. Safety Precautions

1-1. Repair Precaution

Before attempting any repair or detailed tuning, shield the device from RF noise or static electricity discharges.

Use only demagnetized tools that are specifically designed for small electronic repairs, as most electronic parts are sensitive to electromagnetic forces.

Use only high quality screwdrivers when servicing products. Low quality screwdrivers can easily damage the heads of screws.

Use only conductor wire of the properly gauge and insulation for low resistance, because of the low margin of error of most testing equipment.

We recommend 22-gauge twisted copper wire.

Hand-soldering is not recommended, because printed circuit boards (PCBs) can be easily damaged, even with relatively low heat. Never use a soldering iron with a power rating of more than 100 watts and use only lead-free solder with a melting point below 250°C (482°F).

Prior to disassembling the battery charger for repair, ensure that the AC power is disconnected. Always use the replacement parts that are registered in the SEC system. Third-party replacement parts may not function properly.

1. Safety Precautions

1-2. ESD(Electrostatically Sensitive Devices) Precaution

Many semiconductors and ESDs in electronic devices are particularly sensitive to static discharge and can be easily damaged by it. We recommend protecting these components with conductive anti-static bags when you store or transport them.

Always use an anti-static strap or wristband and remove electrostatic buildup or dissipate static electricity from your body before repairing ESDs.

Ensure that soldering irons have AC adapter with ground wires and that the ground wires are properly connected.

Use only desoldering tools with plastic tips to prevent static discharge.

Properly shield the work environment from accidental electrostatic discharge before opening packages containing ESDs.

The potential for static electricity discharge may be increased in low humidity environments, such as air-conditioned rooms. Increase the airflow to the working area to decrease the chance of accidental static electricity discharges.

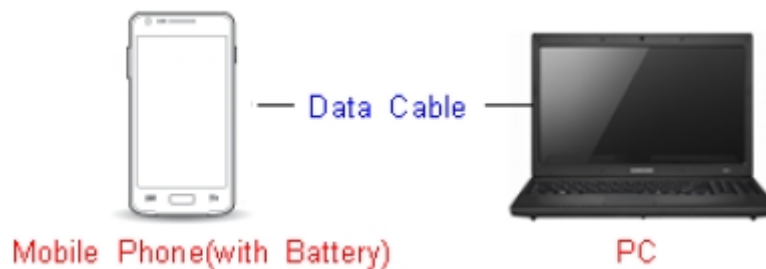
6. Level 1 Repair

6-1. S/W installation

6-1-1. Required items in order to install S/W

- Installation program: Downloader Program ([Odin3 v3.12.5.exe](#))
- Mobile Phone
- Data Cable
- Mobile device specific S/W: Binary files

※ Settings

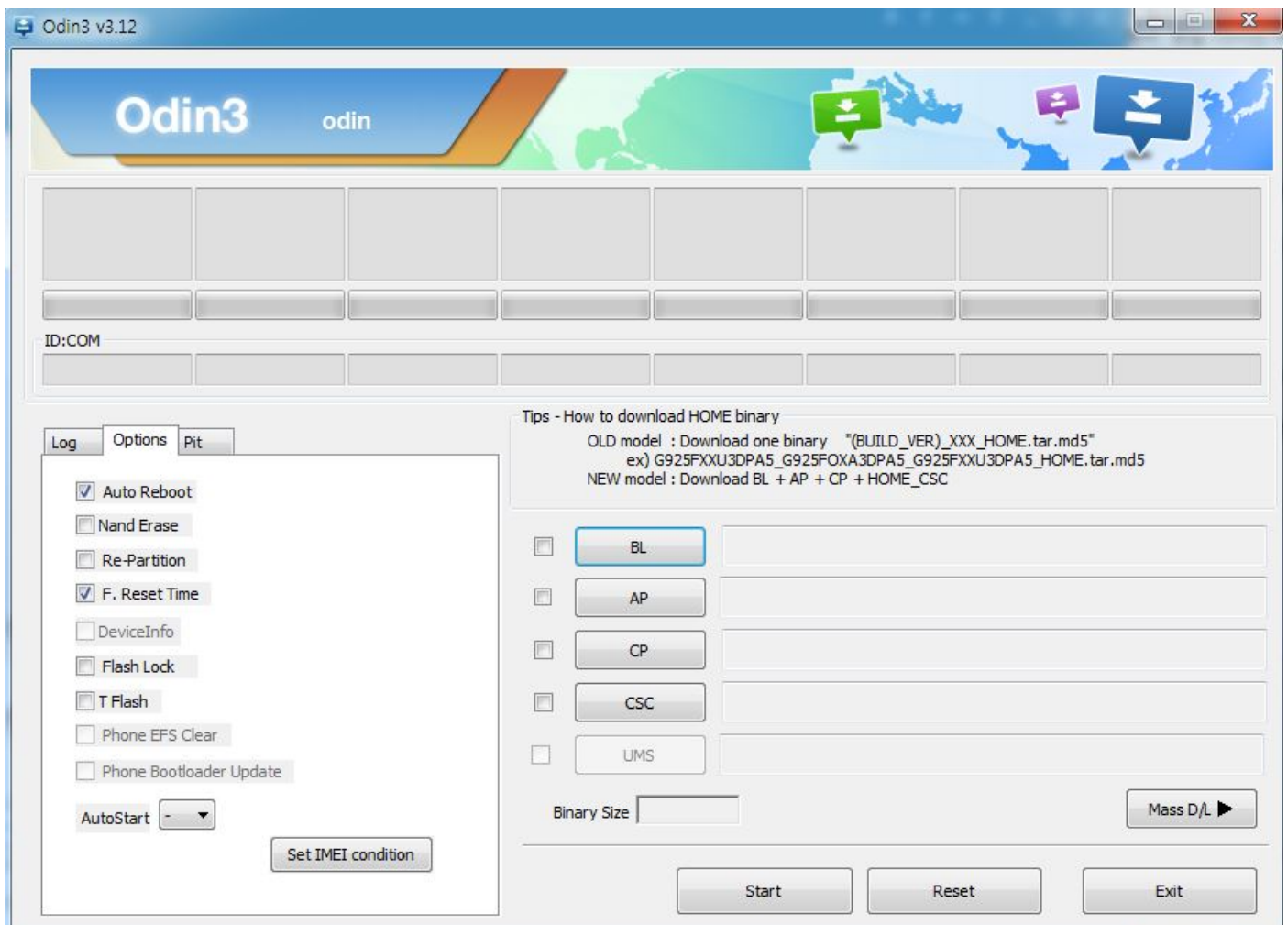


Data Cable : GH39-01710D

6. Level 1 Repair

6-1-2. S/W Installation Program (Downloader program)

- Open up the S/W Installation Program by executing the "**Odin3 v3.12.5.exe**"

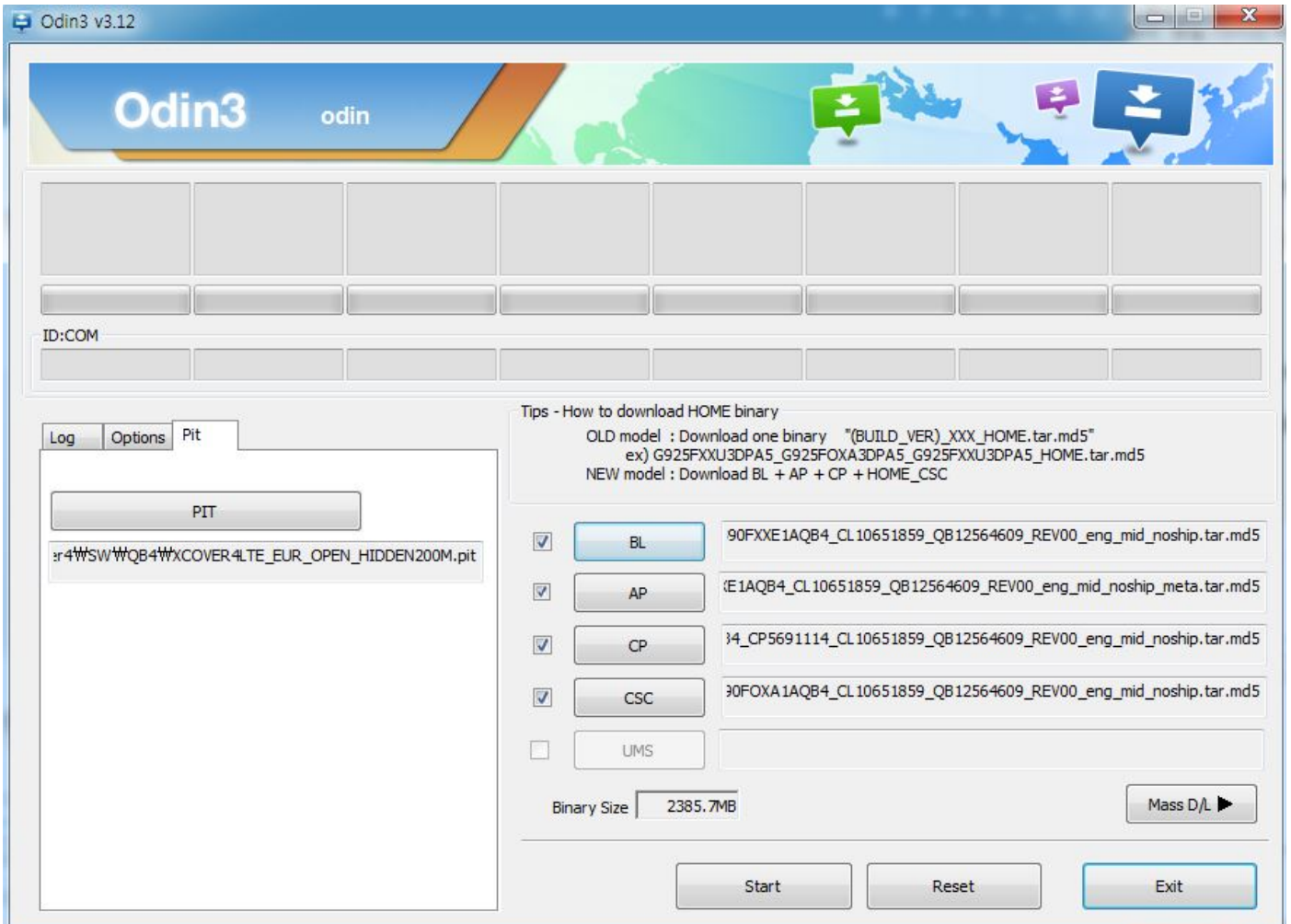


6. Level 1 Repair

1. Enable the check mark by click on the following options,

- Check Auto Reboot, Re-Partition, and F. Reset Time
- Check PIT
- Check BOOTLOADER, PDA, PHONE, and CSC Files

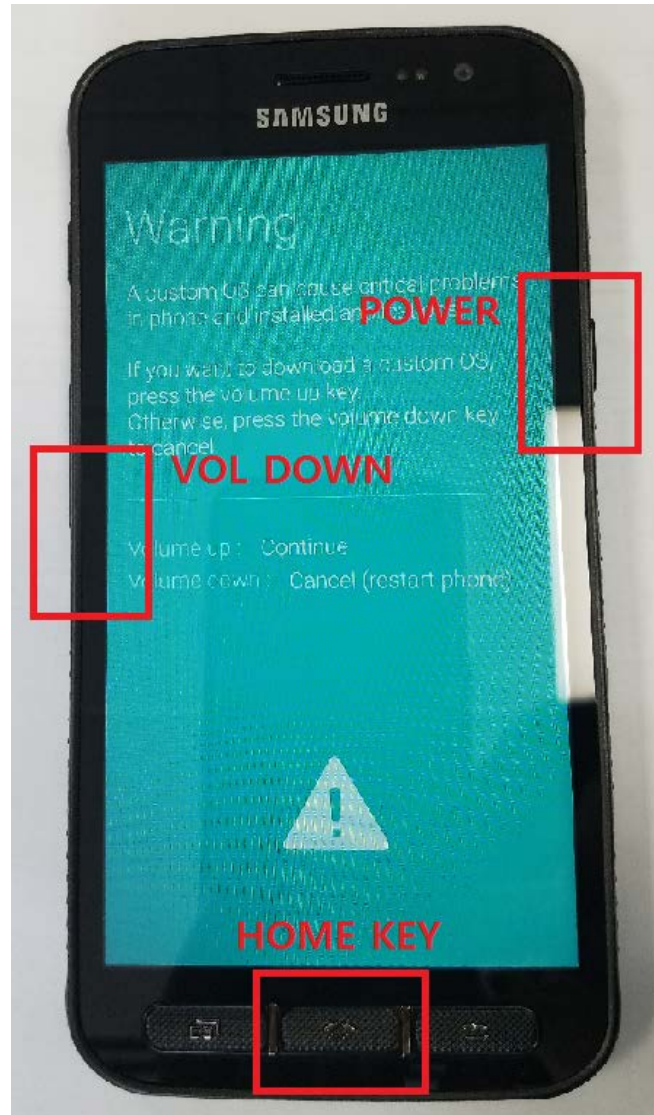
* Note : "Odin v3.12.5 or above" checks MD5 checksum just after file selection.



6. Level 1 Repair

2. Enter into Download Mode

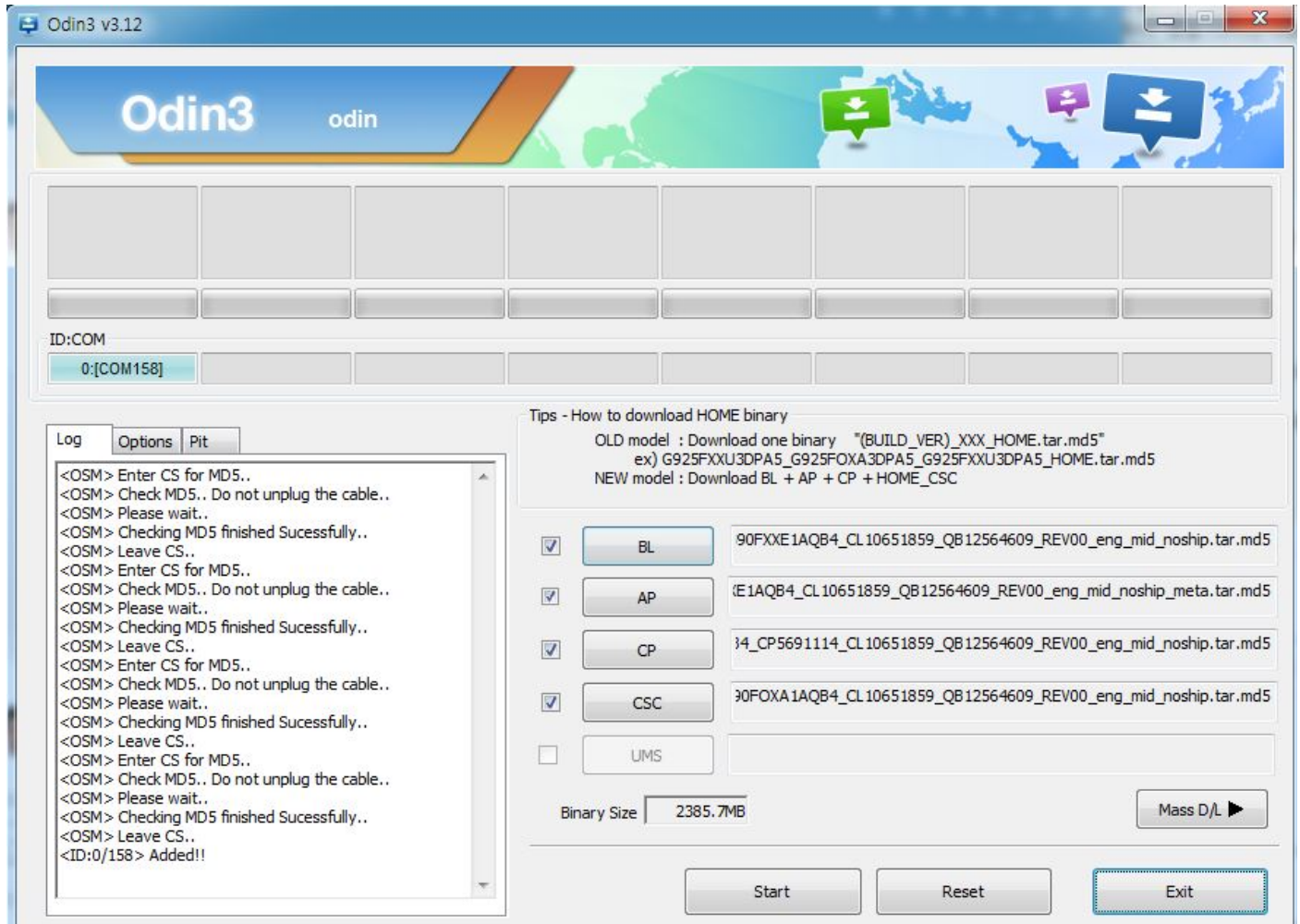
- Enter into Download Mode by pressing Volume Down, Home and Power button simultaneously followed by pressing
- Volume up button as a direction of the phone.



6. Level 1 Repair

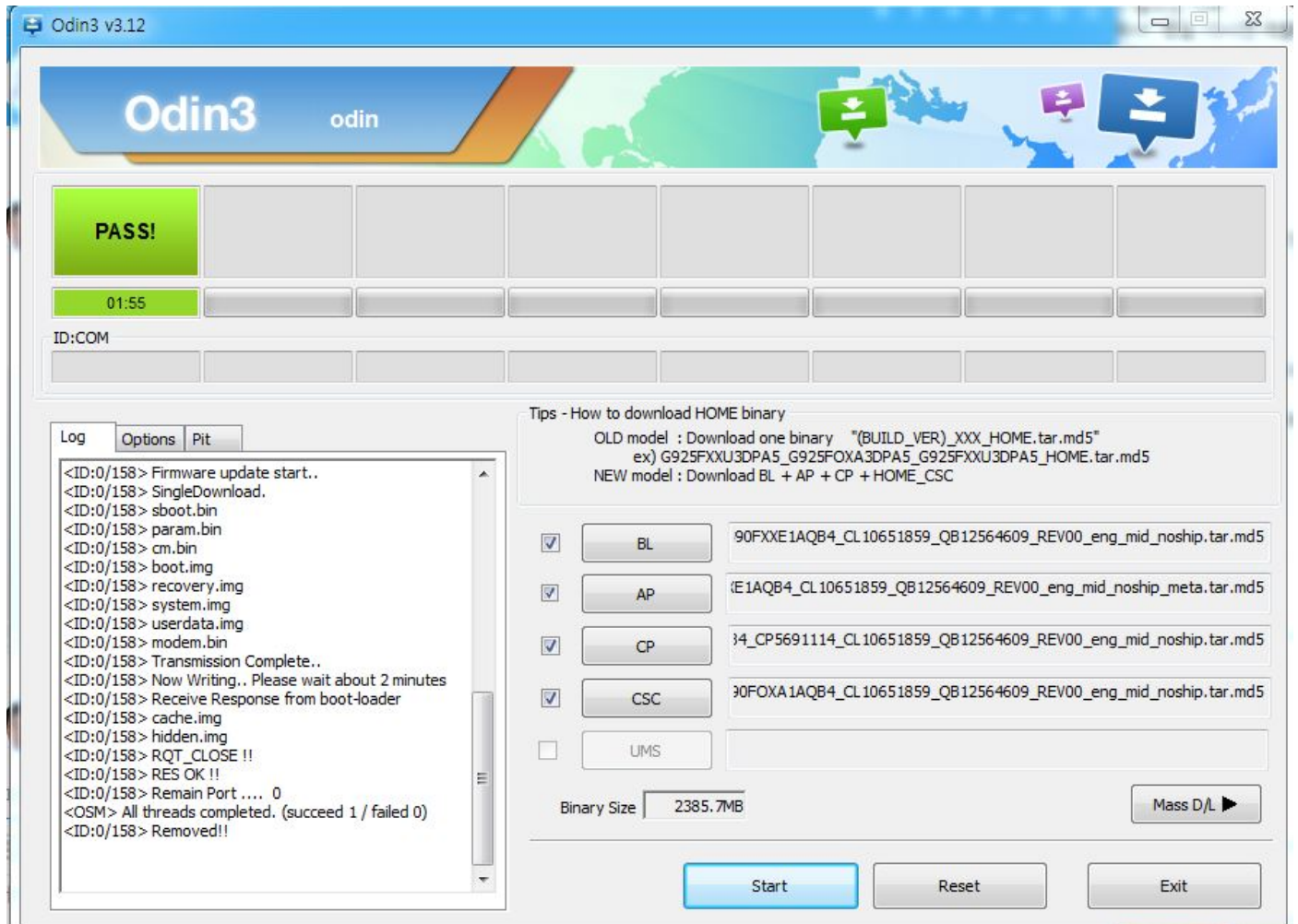
3. Connect the device to PC via Data Cable.

Make sure that the one of communication ports [ID:COM] box is highlighted in sky blue. The device is now connected with the PC and ready to download the binary files in it.



6. Level 1 Repair

4. Start downloading the binary files into the device by clicking Start button on the screen.
The green colored "PASS!" sign will appear on the upper-left box
if the binary files have been successfully downloaded into the device.



5. Disconnect the device from the Data cable.

6. Once the device boots up, you can check the version of the binary file or name by pressing the following code in sequence; ***#1234#**

You can perform Factory Reset by Settings → Accounts → Backup and reset

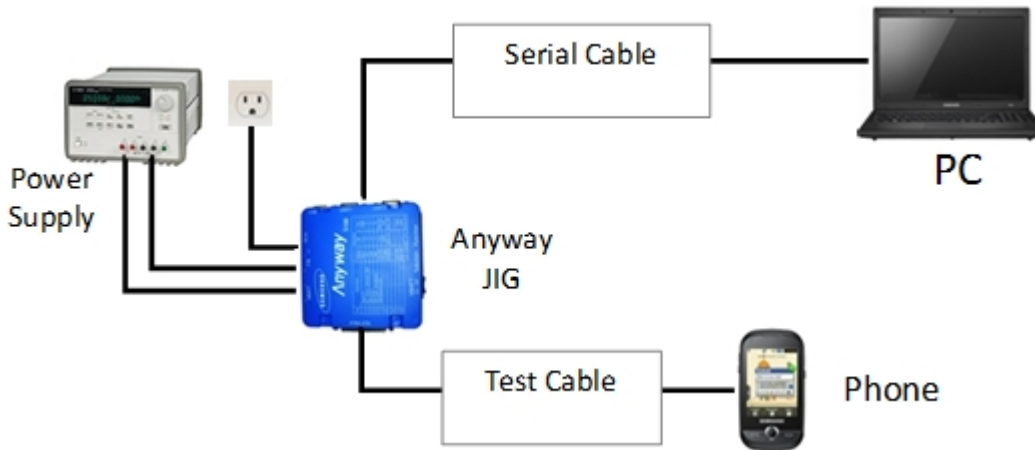
6. Level 1 Repair

6-2 IMEI writing

6-2-1 Preparation

- New IMEI writing Program has been released.
- Supported Model : Models which CAB files are uploaded on HHPsvc INI File category, instead of ini file.
- Refer to below IMEI writing procedure.

- H/W



- S/W

① Library Install	To use Daseul, library files should be installed. Refer to SVC Bulletin “(11-82) Daseul (New IMEI writing Program) Library Install guide_rev1.0”
② Launcher	DASEUL_SVC_Launcher_v3_0_25 or higher -Uploaded on HHPsvc Notice
③ Runtime File	1. DASEUL_Runtime_Ver_3.1.139.0.CAB or higher -Uploaded on HHPsvc Notice 2. Make ‘ModelName’ folder at the same position with launcher & Runtime file.
④ Model File	Copy Model File under the ‘Model Name’ folder

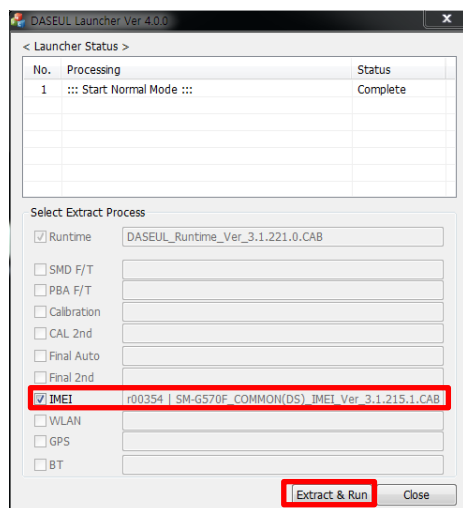
6. Level 1 Repair

6-2-2 IMEI writing Process

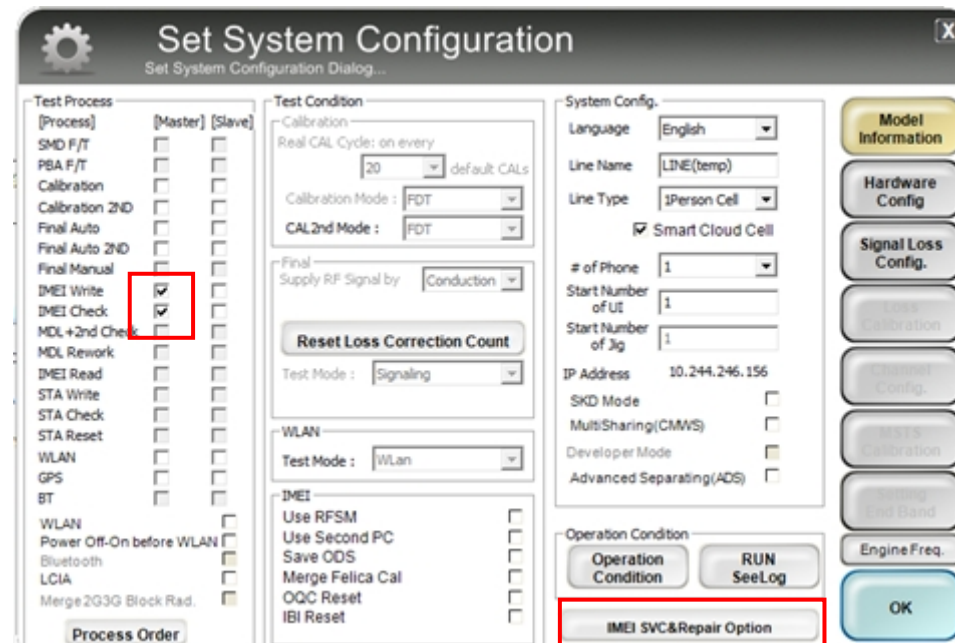
1. Run DASEUL_SVC_Launcher_v3.0.10.exe

 DASEUL_Launcher_v3.0.27.exe

2. Select IMEI and then Extract & Run

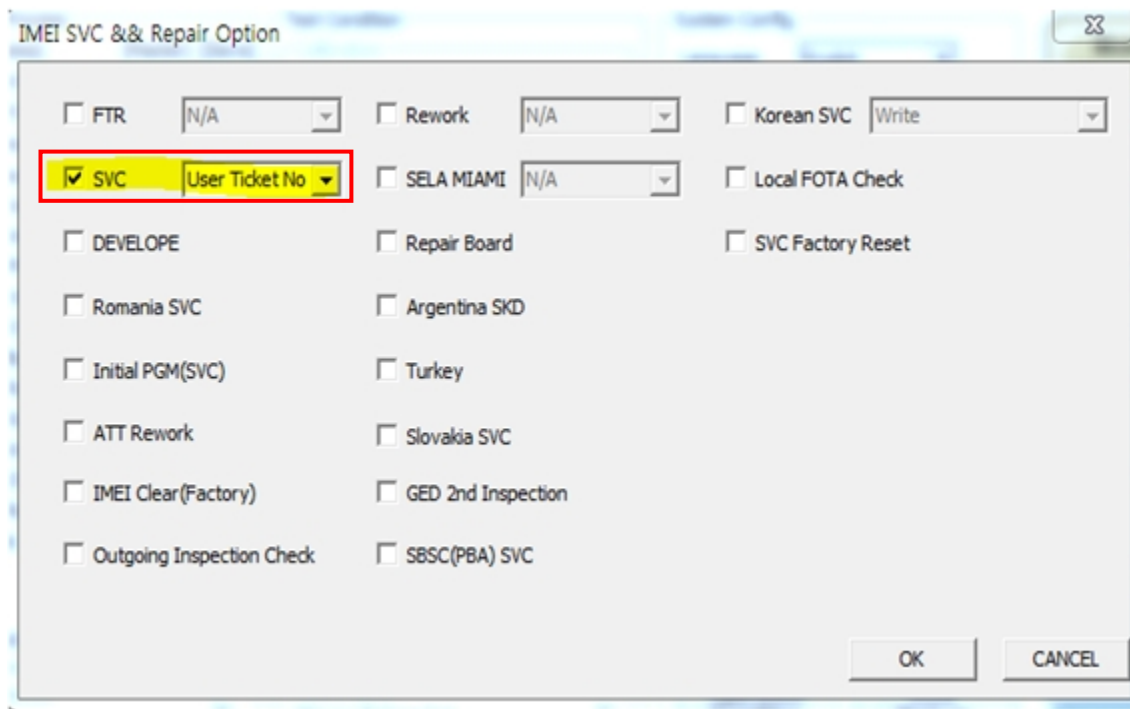


3. Check 'IMEI Write / IMEI Check', and click 'IMEI SVC & Repair Option'



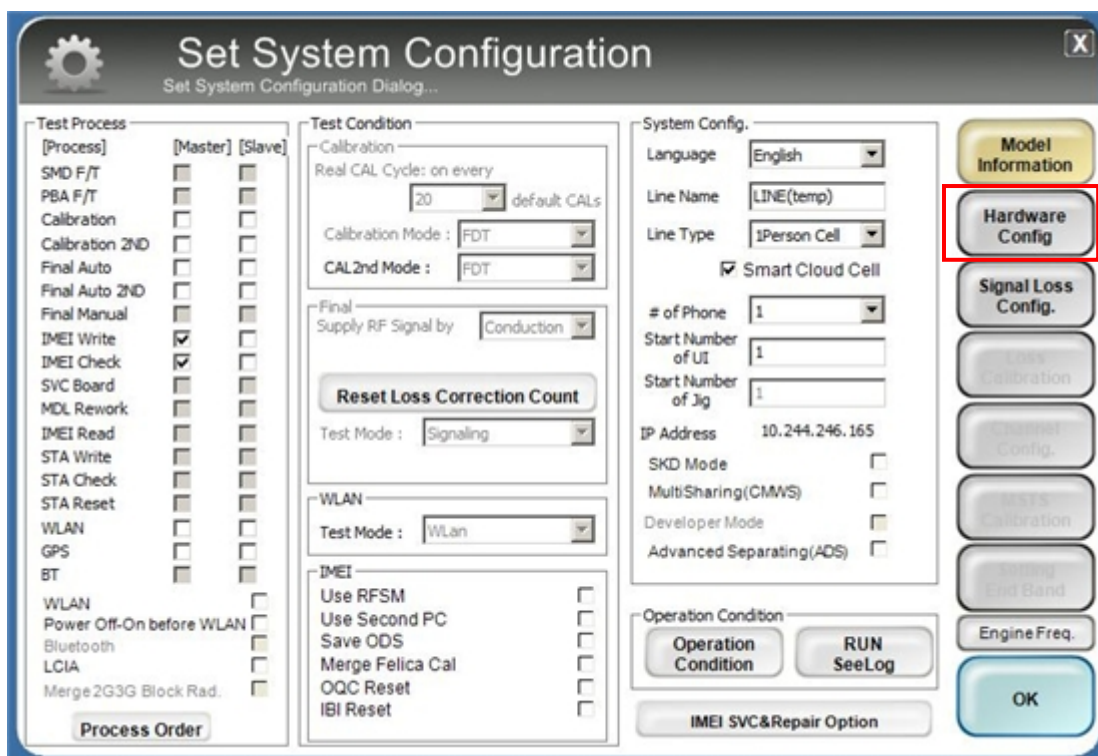
6. Level 1 Repair

4. Check 'SVC , User Ticket No' and click OK



The dialog box titled "IMEI SVC && Repair Option" contains various checkboxes and dropdown menus. The "SVC" checkbox is checked, and the "User Ticket No" dropdown menu is selected. Other options include FTR, Rework, Korean SVC, Sela Miami, Local FOTA Check, DEVELOPE, Repair Board, SVC Factory Reset, Romania SVC, Argentina SKD, Initial PGM(SVC), Turkey, ATT Rework, Slovakia SVC, IMEI Clear(Factory), GED 2nd Inspection, Outgoing Inspection Check, and SBSC(PBA) SVC. The "OK" and "CANCEL" buttons are at the bottom right.

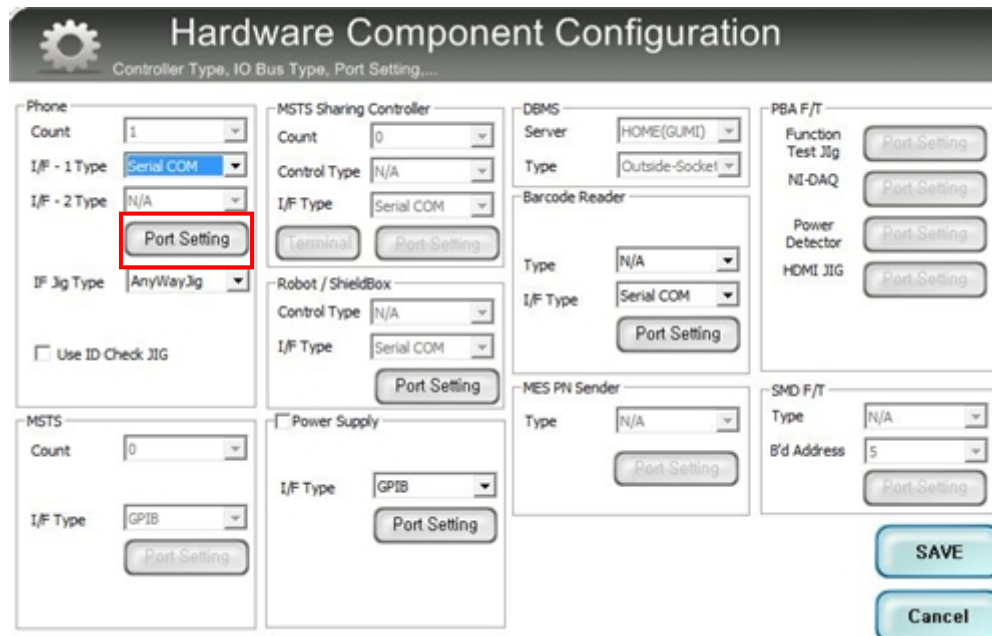
5. Click 'Hardware Config'



The "Set System Configuration" dialog box is divided into several sections. The "Test Process" section on the left lists various tests with checkboxes for [Process], [Master], and [Slave]. The "Test Condition" section in the middle includes calibration settings and a "Reset Loss Correction Count" button. The "System Config." section on the right includes language, line name, line type, and other configuration options. The "Hardware Config" button is highlighted in the right sidebar. The "OK" button is at the bottom right.

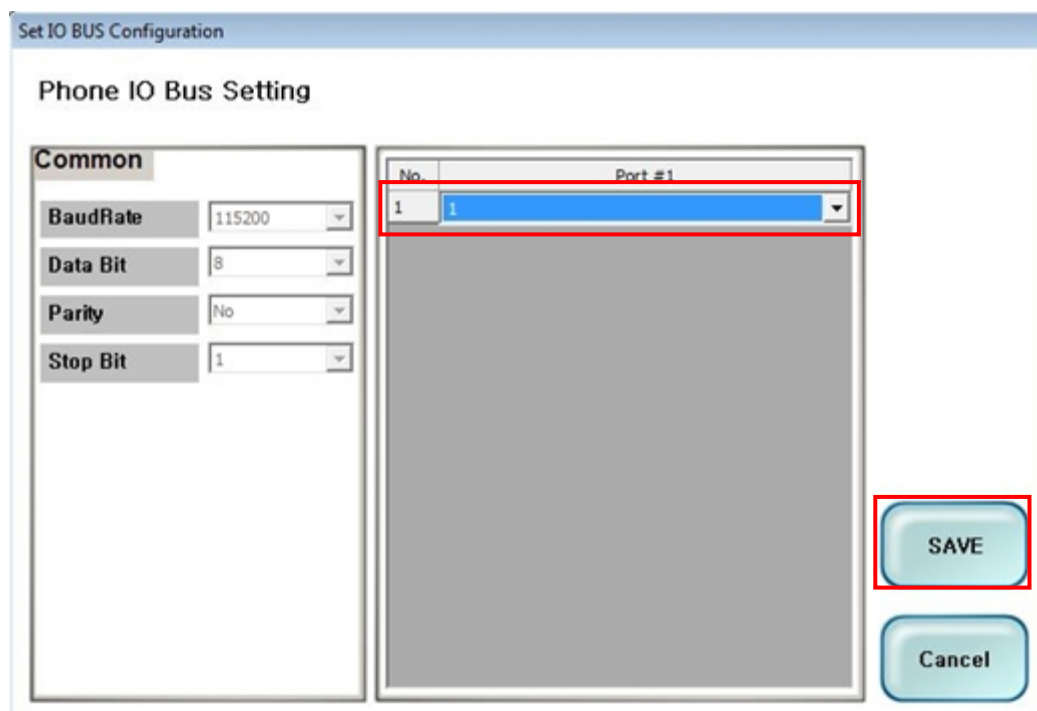
6. Level 1 Repair

6. Click 'Port Setting'



The 'Hardware Component Configuration' window is divided into several sections. The 'Phone' section on the left includes fields for 'Count' (1), 'I/F - 1 Type' (Serial COM), 'I/F - 2 Type' (N/A), 'IF Jig Type' (AnyWayJig), and a checkbox for 'Use ID Check JIG'. The 'MSTS' section below it has 'Count' (0) and 'I/F Type' (GP1B). The 'MSTS Sharing Controller' section has 'Count' (0), 'Control Type' (N/A), 'I/F Type' (Serial COM), and a 'Terminal' button. The 'Robot / ShieldBox' section has 'Control Type' (N/A), 'I/F Type' (Serial COM), and a 'Port Setting' button. The 'Power Supply' section has 'I/F Type' (GP1B) and a 'Port Setting' button. The 'DEMS' section has 'Server' (HOME(GUMI)) and 'Type' (Outside-Socket). The 'Barcode Reader' section has 'Type' (N/A) and 'I/F Type' (Serial COM), with a 'Port Setting' button. The 'MES PN Sender' section has 'Type' (N/A) and a 'Port Setting' button. The 'PBA F/T' section on the right includes buttons for 'Function Test Jig', 'NI-DAQ', 'Power Detector', and 'HDMI JIG', each with a 'Port Setting' button. The 'SMD F/T' section has 'Type' (N/A), 'B'd Address' (5), and a 'Port Setting' button. At the bottom right are 'SAVE' and 'Cancel' buttons. A red box highlights the 'Port Setting' button in the 'Phone' section.

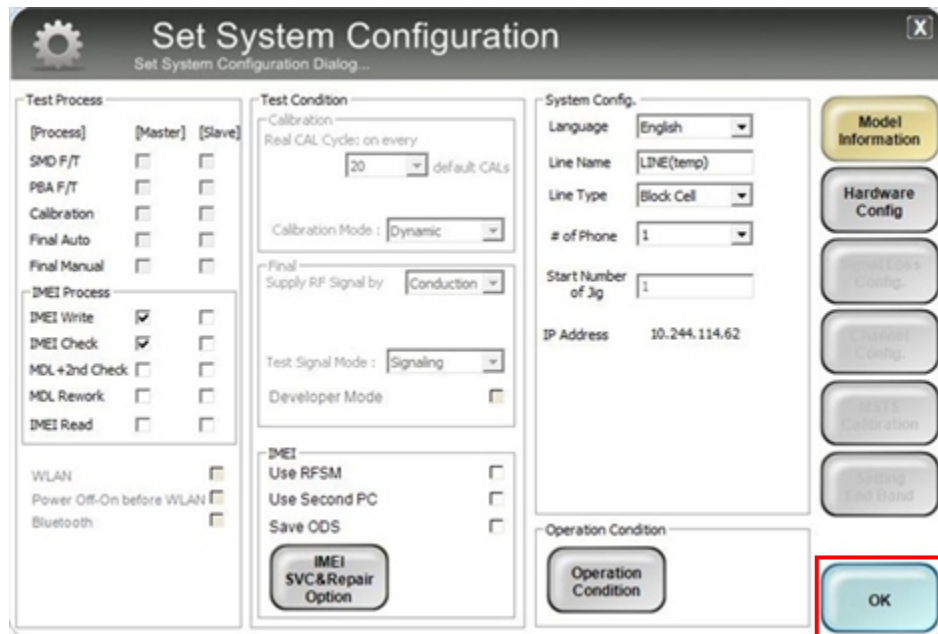
7. Select Port Number and SAVE



The 'Set IO BUS Configuration' window shows 'Phone IO Bus Setting'. On the left, the 'Common' tab is active, showing 'BaudRate' (115200), 'Data Bit' (8), 'Parity' (No), and 'Stop Bit' (1). On the right, a table titled 'Port #1' has two columns: 'No.' and 'Port #1'. The first row shows '1' in the 'No.' column and '1' in the 'Port #1' column. A red box highlights the '1' in the 'Port #1' column. At the bottom right are 'SAVE' and 'Cancel' buttons, with a red box highlighting the 'SAVE' button.

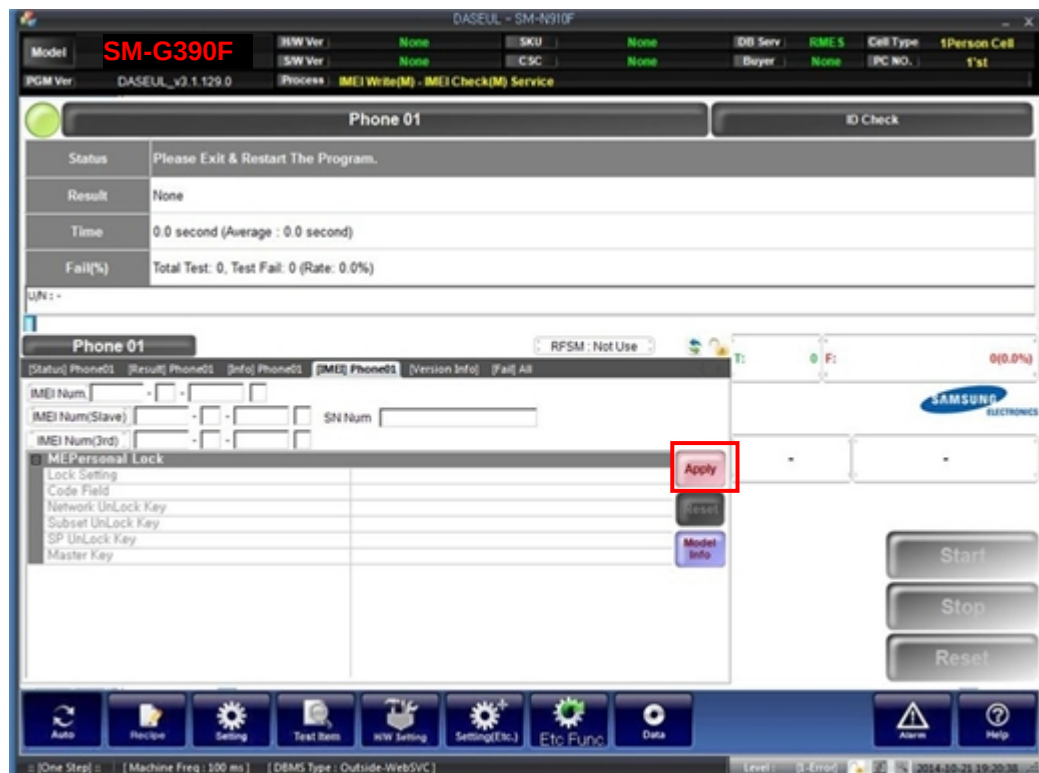
6. Level 1 Repair

8. Click OK to proceed



The 'Set System Configuration' dialog box is shown. It contains several sections: 'Test Process' with checkboxes for SMD F/T, PSA F/T, Calibration, Final Auto, Final Manual, IMEI Write, IMEI Check, MDL+2nd Check, MDL Rework, and IMEI Read; 'Test Condition' with a 'Calibration' section (Real CAL Cycle: on every 20, Calibration Mode: Dynamic) and a 'Final' section (Supply RF Signal by: Conduction, Test Signal Mode: Signaling, Developer Mode); 'System Config.' with fields for Language (English), Line Name (LINE(temp)), Line Type (Block Cell), # of Phone (1), Start Number of Jig (1), and IP Address (10.244.114.62); and 'Operation Condition' with a button labeled 'IMEI SVC&Repair Option'. On the right side, there is a vertical stack of buttons: 'Model Information', 'Hardware Config', 'Signal Test Config.', 'Channel Config.', 'WLAN Calibration', and 'Setting End Band'. At the bottom right, there is a large blue 'OK' button highlighted with a red rectangle.

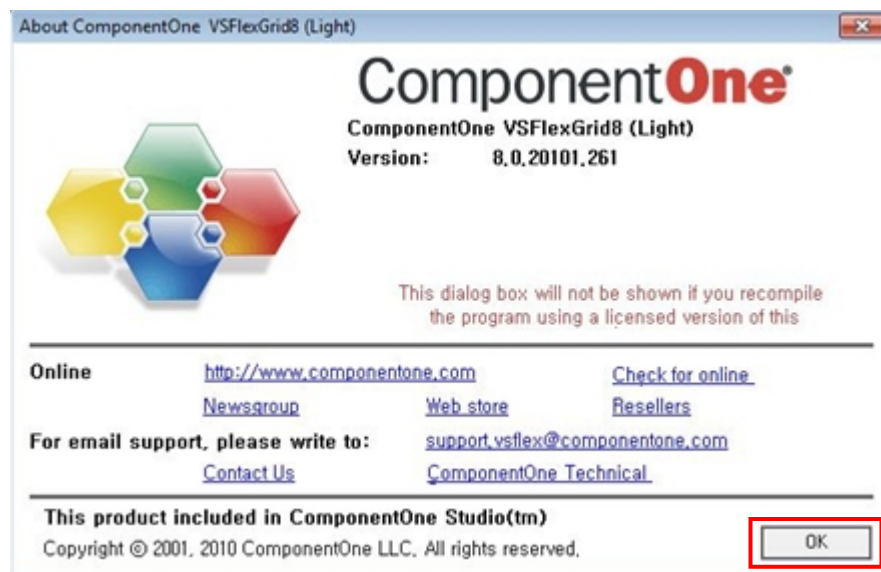
9. Click Model Info and OK when pop-up shows



The 'Phone 01 ID Check' pop-up is shown. It displays the status 'Please Exit & Restart The Program.' and the result 'None'. The time taken is '0.0 second (Average : 0.0 second)' and the failure rate is 'Total Test: 0, Test Fail: 0 (Rate: 0.0%)'. Below this, there is a section for 'Phone 01' with fields for IMEI Num, IMEI Num(Slave), IMEI Num(3rd), and SN Num. To the right of these fields is a red 'Apply' button highlighted with a red rectangle. Below the 'Apply' button is a 'Model Info' button. At the bottom right, there are buttons for 'Start', 'Stop', and 'Reset'. The bottom of the window shows a status bar with various icons and text: 'Auto', 'Receive', 'Setting', 'Test Item', 'Wire Setting', 'Setting(Etc.)', 'Etc Func', 'Data', 'Alarm', and 'Help'. The status bar also displays 'Machine Freq : 100 ms', 'DBMS Type : Outside-WebSVC', and 'Level : 3-4msec'.

6. Level 1 Repair

10. Click OK

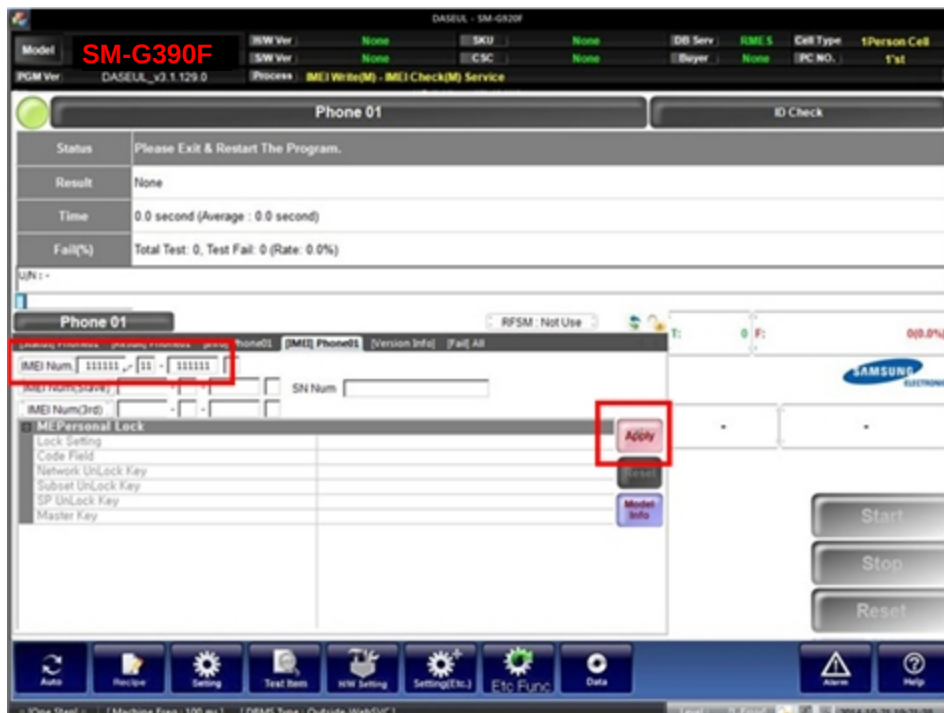


11. Input SKU_CODE and BUYER, then click Save button.

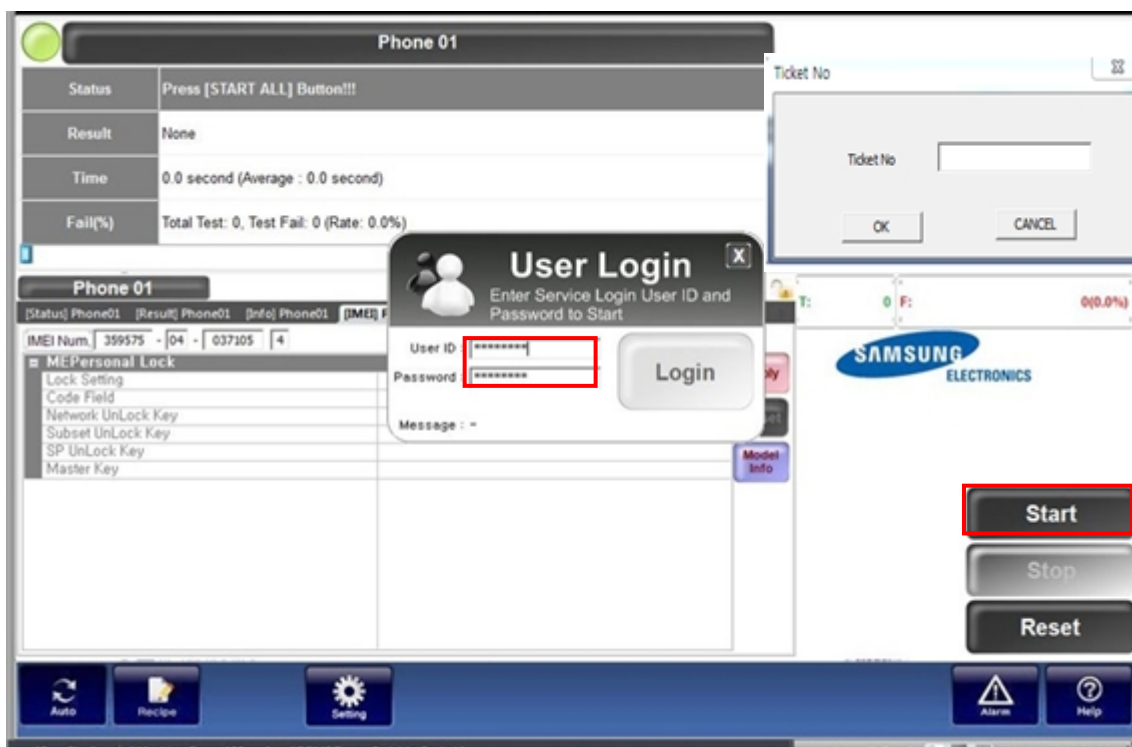
※ Refer to HHPsvc→IMEI Review to check SKU Code and buyer

6. Level 1 Repair

12. Input IMEI Number and click Apply



13. ① Click Start, and input IMEI writing ID and Password → ② input Ticket No

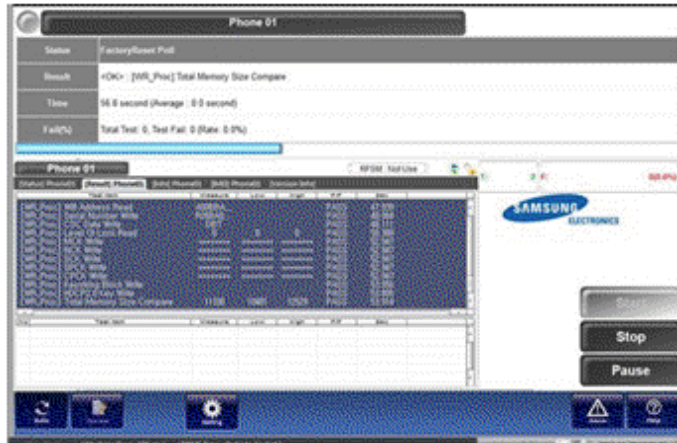


6. Level 1 Repair

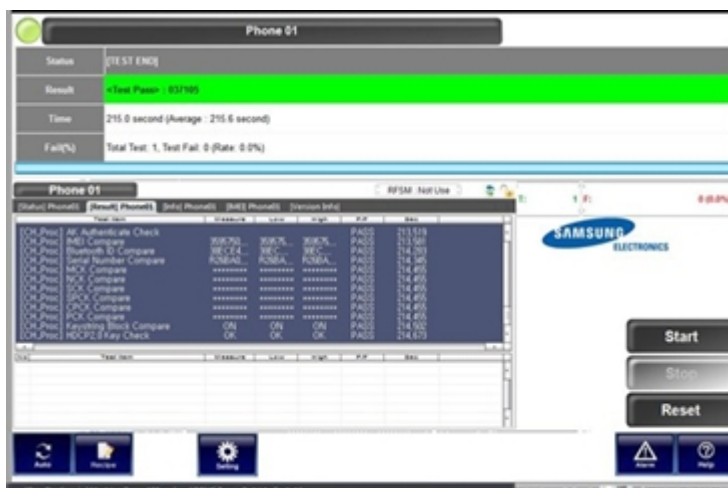
14. Connect the phone to Anyway JIG

※ When you connect the phone, the phone should be turned off.
After connecting the phone, the phone will be booted automatically.

15. IMEI Writing Proceeding



16. IMEI Writing Success



6. Level 1 Repair

6-3. RF Calibration

6-3-1. Required items in order to calibrate RF

- Installation program: RF Calibration Program
 - Daseul_Launcher_vx.x.xx.exe
 - Daseul_CAL_ALL_Runtime_x.x.xxx.x.CAB
 - Model File ([SM-G390F_COMMON\(CSC\)_IMEI_Ver_3.1.260.1.CAB](#))

※ It is required to use the latest program.

- [SM-G390F](#) Mobile Phone
- R&S CMW500
- E3632A Power Supply
- GPIB Cable (2ea)
- JIG BOX (GH81-11888A)
- Adapter (GH81-11888K)
- UART Serial Cable

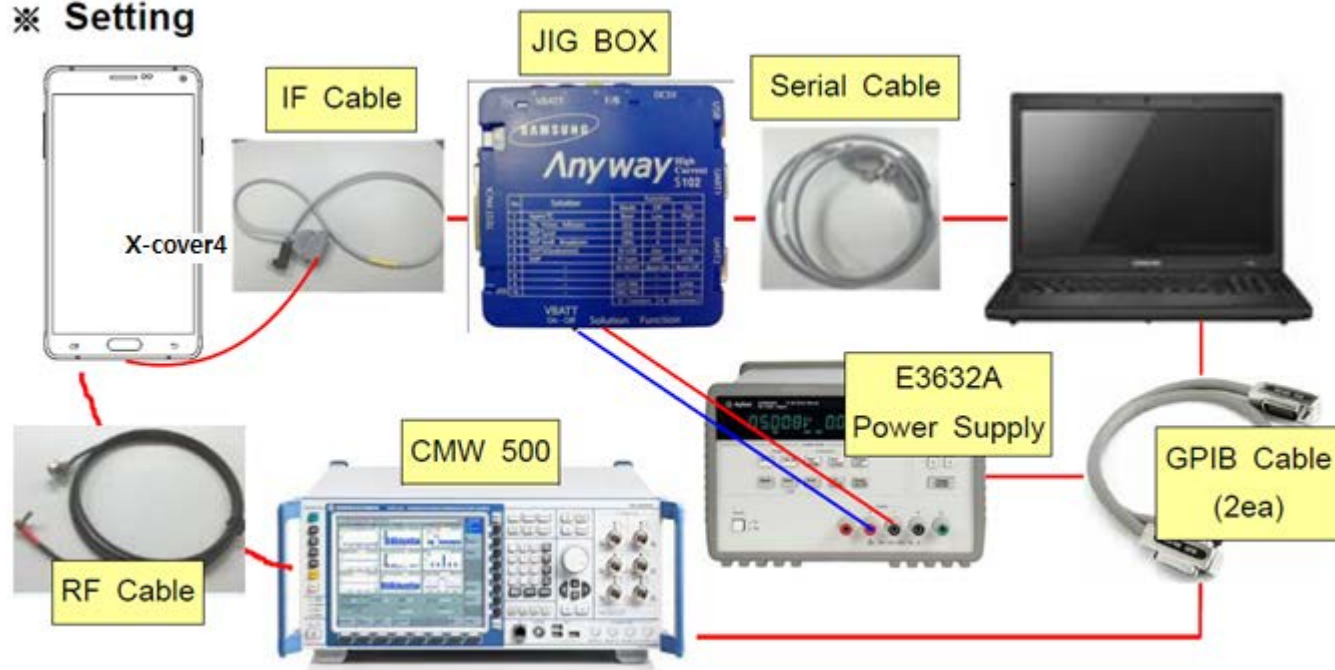
- Table of test cables

IF Cable	GH81-10631A
	11 pin
RF Cable (Manual)	GH81-11962G
	1.35T/1750mm 

6. Level 1 Repair

- RF CAL Line

※ Setting



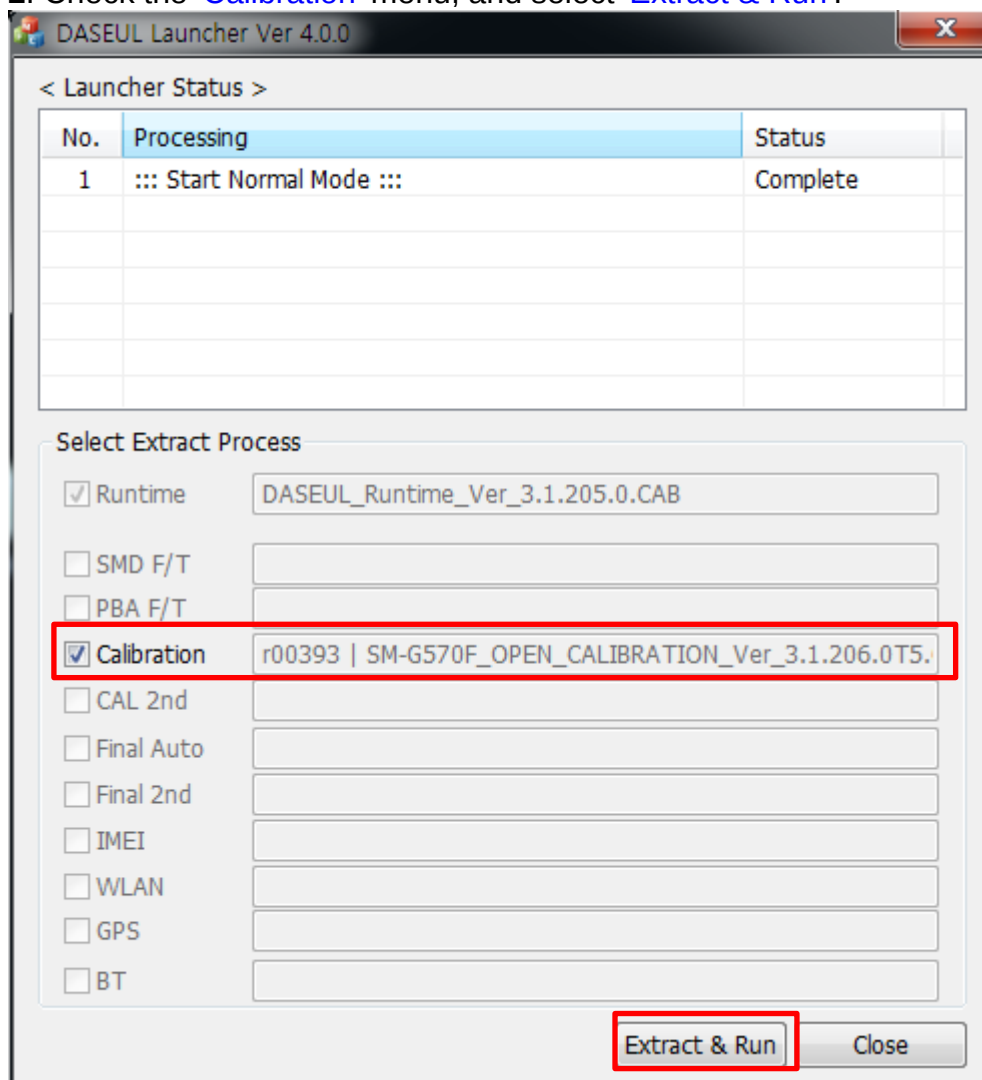
6. Level 1 Repair

6-3-2. RF Calibration Program

1. Run the RF Calibration Program Launcher, 'DASEUL_Launcher_vx.x.xx.exe'.

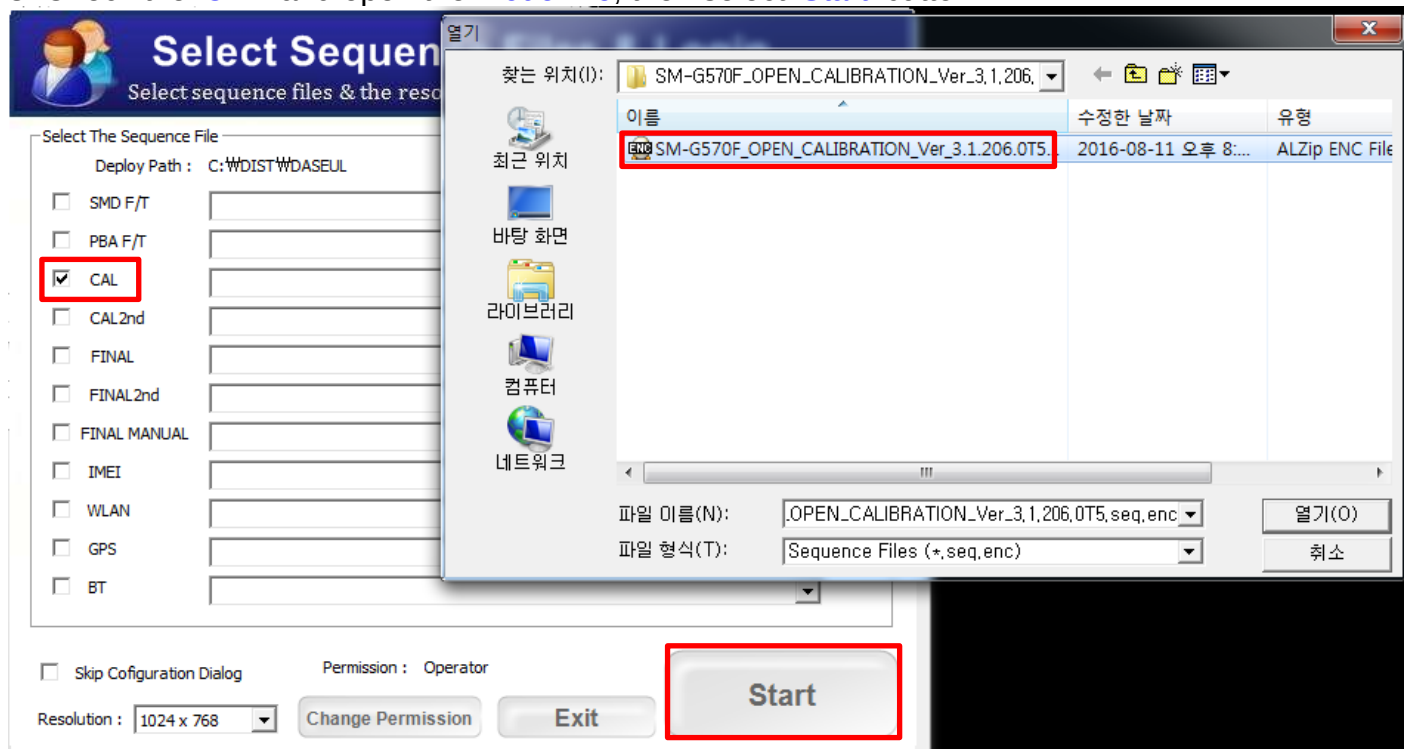
-  DASEUL_CAL_ALL_Component_r00393.CAB
-  DASEUL_CAL_ALL_Runtime_3.1.205.0_r00393.CAB
-  DASEUL_Launcher_v4.0.0.exe
-  DASEUL_Runtime_Ver_3.1.205.0.CAB
-  SM-G570F_OPEN_CALIBRATION_Ver_3.1.206.0T5.CAB

2. Check the 'Calibration' menu, and select 'Extract & Run'.



6. Level 1 Repair

3. Check the 'CAL' and open the [model file](#), then select 'Start' button.



6. Level 1 Repair

4. Change the Line Type to 'Block Cell' and disable 'Smart Cloud Cell'.

Set System Configuration
Set System Configuration Dialog...

Test Process

[Process]	[Master]	[Slave]
SMD F/T	☐	☐
PBA F/T	☐	☐
Calibration	☒	☐
Calibration 2ND	☐	☐
Final Auto	☐	☐
Final Auto 2ND	☐	☐
Final Manual	☐	☐
IMEI Write	☐	☐
IMEI Check	☐	☐
MDL+2nd Check	☐	☐
MDL Rework	☐	☐
IMEI Read	☐	☐
STA Write	☐	☐
STA Check	☐	☐
STA Reset	☐	☐
WLAN	☐	☐
GPS	☐	☐
BT	☐	☐
WLAN	☐	☐
Power Off-On before WLAN	☐	☐
Bluetooth	☐	☐
LCIA	☐	☐
Merge 2G3G Block Rad.	☐	☐

Test Condition

Calibration
Real CAL Cycle: on every default CALs

Calibration Mode :

CAL2nd Mode :

Final
Supply RF Signal by

- Loss Cal ☐

Reset Loss Correction Count

Test Mode :

WLAN
Test Mode :

IMEI
Use RFSM ☐
Use Second PC ☐
Save ODS ☐
Merge Felica Cal ☐
OQC Reset ☐
IBI Reset ☐

System Config.

Language

Line Name

Line Type

☐ Smart Cloud Cell

of Phone

Start Number of UI

Start Number of Jig

IP Address

SKD Mode ☐

MultiSharing(CMWS) ☐

Developer Mode ☐

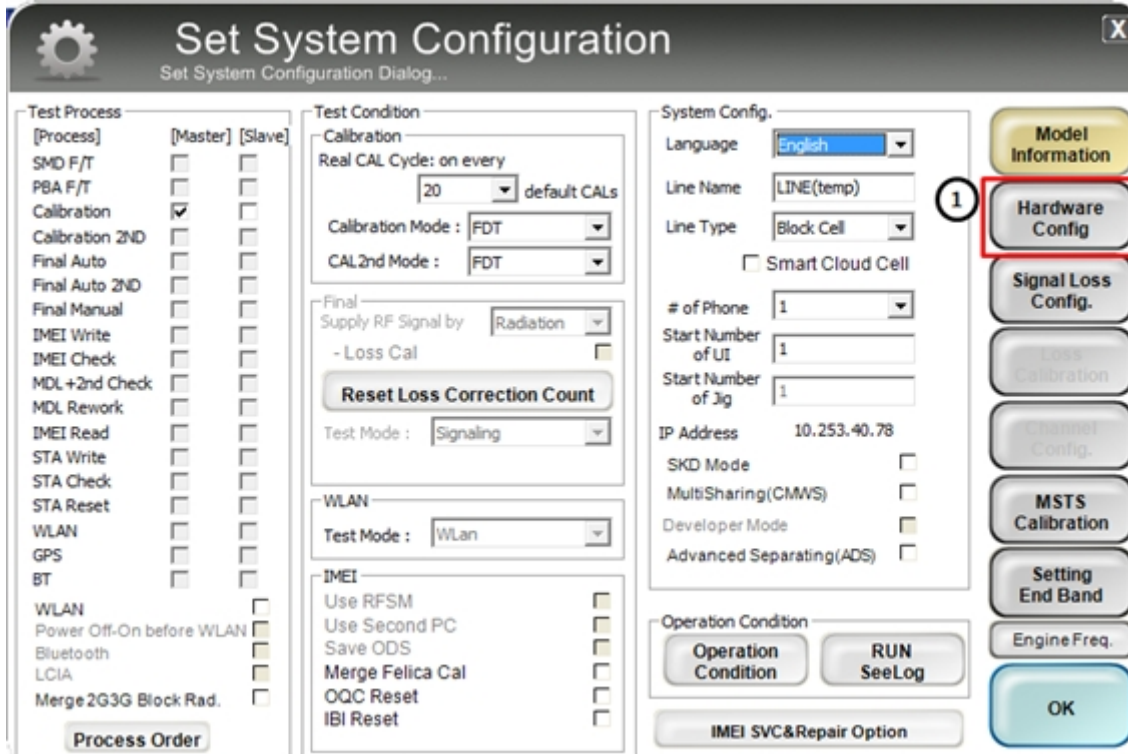
Advanced Separating(ADS) ☐

Operation Condition

Model Information

6. Level 1 Repair

- Set the GPIB address of MSTs(CMW500) and Power Supply(E3632A) to enter 'Hardware Config' and 'Save'. (Check the GPIB address of equipments in advance)



Set System Configuration
Set System Configuration Dialog...

Test Process

[Process]	[Master]	[Slave]
SMD F/T	☐	☐
PBA F/T	☐	☐
Calibration	☒	☐
Calibration 2ND	☐	☐
Final Auto	☐	☐
Final Auto 2ND	☐	☐
Final Manual	☐	☐
IMEI Write	☐	☐
IMEI Check	☐	☐
MDL +2nd Check	☐	☐
MDL Rework	☐	☐
IMEI Read	☐	☐
STA Write	☐	☐
STA Check	☐	☐
STA Reset	☐	☐
WLAN	☐	☐
GPS	☐	☐
BT	☐	☐
WLAN	☐	☐
Power Off-On before WLAN	☐	☐
Bluetooth	☐	☐
LCIA	☐	☐
Merge 2G3G Block Rad.	☐	☐

Test Condition

Calibration
Real CAL Cycle: on every 20 default CALs

Calibration Mode: FDT
CAL2nd Mode: FDT

Final
Supply RF Signal by: Radiation
- Loss Cal ☐

Reset Loss Correction Count

Test Mode: Signaling

WLAN
Test Mode: WLAN

IMEI
Use RFSM ☐
Use Second PC ☐
Save ODS ☐
Merge Felica Cal ☐
OQC Reset ☐
IBI Reset ☐

System Config.

Language: English
Line Name: LINE(temp)
Line Type: Block Cell
☐ Smart Cloud Cell

of Phone: 1
Start Number of UT: 1
Start Number of Jig: 1

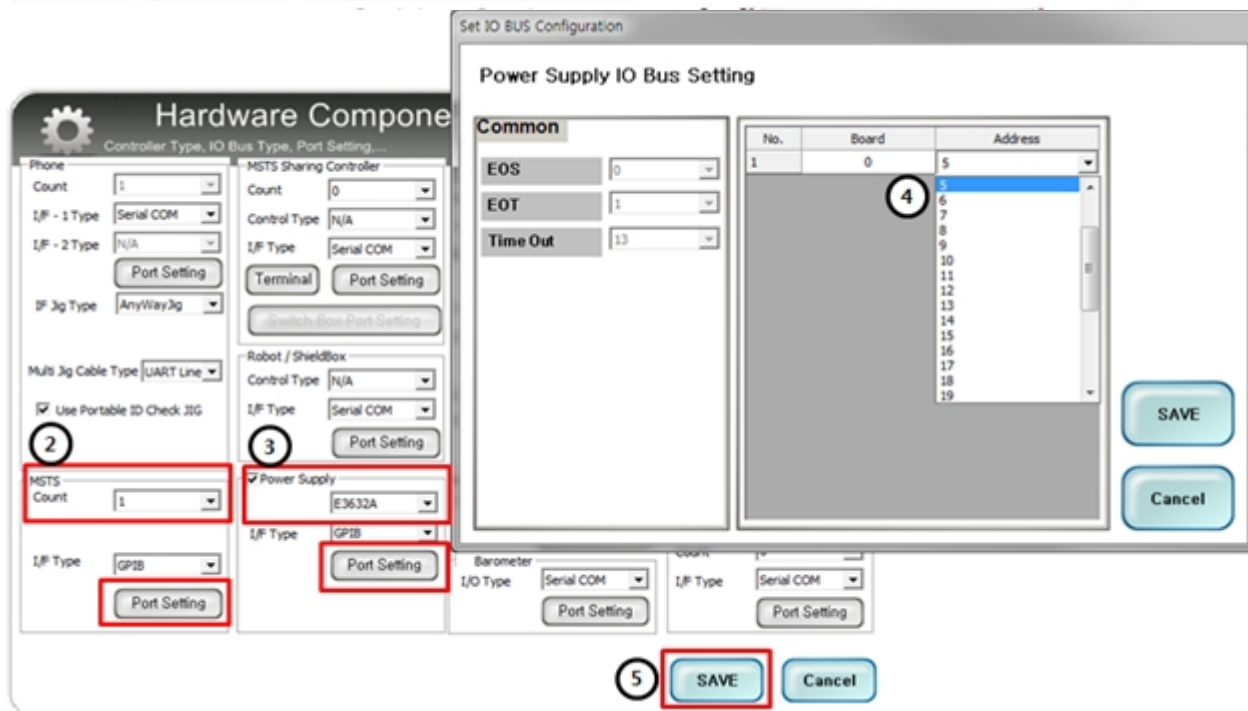
IP Address: 10.253.40.78

SKD Mode ☐
MultiSharing(CMWS) ☐
Developer Mode ☐
Advanced Separating(ADS) ☐

Operation Condition
RUN SeeLog

IMEI SVC&Repair Option

Model Information
Hardware Config
Signal Loss Config.
Loss Calibration
Channel Config.
MSTS Calibration
Setting End Band
Engine Freq.
OK



Hardware Component
Controller Type, IO Bus Type, Port Setting...

Phone Count: 1
I/F - 1 Type: Serial COM
I/F - 2 Type: N/A
I/F 3g Type: AnyWay3g
Multi 3g Cable Type: UART Line
☒ Use Portable ID Check JIG

MSTS Count: 1
I/F Type: GPIB
Port Setting

MSTS Sharing Controller Count: 0
Control Type: N/A
I/F Type: Serial COM
Terminal Port Setting
Switch Box Port Setting

Robot / ShieldBox Control Type: N/A
I/F Type: Serial COM
Port Setting

☒ Power Supply E3632A
I/F Type: GPIB
Port Setting

Set IO BUS Configuration
Power Supply IO Bus Setting

Common
EOS: 0
EOT: 1
Time Out: 13

No.	Board	Address
1	0	5
2		6
3		7
4		8
5		9
6		10
7		11
8		12
9		13
10		14
11		15
12		16
13		17
14		18
15		19

SAVE
Cancel

SAVE
Cancel

6. Level 1 Repair

6. Press 'OK' to start RF Calibration after completing all settings.

The screenshot displays the Samsung Service Tool (SST) interface. The top section is the 'Set System Configuration' dialog box, which is divided into several tabs: 'Test Process', 'Test Condition', 'System Config.', and 'Model Information'. The 'Test Process' tab is active, showing a list of test items with checkboxes for 'Master' and 'Slave' modes. The 'Test Condition' tab is also visible, showing settings for 'Calibration' (Real CAL Cycle: on every 20 default CALs, Calibration Mode: FDT, CAL2nd Mode: FDT) and 'WLAN' (Test Mode: WLAN). The 'System Config.' tab shows settings for 'Language' (English), 'Line Name' (LINE(temp)), 'Line Type' (Block Cell), and 'Smart Cloud Cell' (unchecked). The 'Model Information' tab shows 'Model' (SM-G390F), 'H/W Ver' (REV0.5), 'SKU' (xx), 'DB Serv' (HOME(GUMI)), 'Cell Type' (Block Cell), 'Buyer' (XX), and 'PC NO.' (NONE). The 'OK' button is highlighted with a red box and a circled '1'.

The bottom section of the screenshot shows the 'Phone 01' test results screen. It displays a table of test results for 'Phone 01' with columns for 'Time', 'No.', 'Item', and 'Status'. The test results show various initialization steps completed, such as 'RTCRead', 'BatteryVoltageC...', 'SetTestNV', 'MD5_Enable', 'FactoryTestLog...', 'BackUp', 'SleepCurrent', 'EndCalibration', 'UlnitTestStep', 'JIG Open IOBus', 'Set JIG Solution', 'Get Reference Current', 'RefCurrent[0] = -0.21657[mA]', 'Reference Current = -0.2', 'Get MSTs License', 'MSTs License Info', 'Get MSTs Reset', 'Initial Step End, TEST READY!', and 'Initial Step End, TEST READY!'. The 'Status' column shows '0' for most items, indicating successful completion. The 'Fail(%)' is 0.0%. The 'SAMSUNG ELECTRONICS' logo is visible on the right side of the screen. The bottom navigation bar includes buttons for 'Auto', 'Recipe', 'Setting', 'Test Item', 'H/W Setting', 'Setting(Etc.)', 'Etc Func', 'Data', 'Alarm', and 'Help'.